



Characteristics ( $T_j = 25^\circ\text{C}$ )Kennwerte ( $T_j = 25^\circ\text{C}$ )

		Min.	Typ.	Max.
Base saturation voltage – Basis-Sättigungsspannung <sup>1)</sup>				
$I_C = 10\text{ mA}, I_B = 0.25\text{ mA}$	$V_{BEsat}$	600 mV	–	850 mV
$I_C = 50\text{ mA}, I_B = 1.25\text{ mA}$	$V_{BEsat}$	700 mV	–	1050 mV
DC current gain – Kollektor-Basis-Stromverhältnis <sup>1)</sup>				
$V_{CE} = 5\text{ V}, I_C = 10\text{ }\mu\text{A}$	BCW 60B	$h_{FE}$	20	–
	BCW 60C	$h_{FE}$	40	–
	BCW 60D	$h_{FE}$	100	–
$V_{CE} = 5\text{ V}, I_C = 2\text{ mA}$	BCW 60B	$h_{FE}$	180	–
	BCW 60C	$h_{FE}$	250	–
	BCW 60D	$h_{FE}$	380	–
$V_{CE} = 1\text{ V}, I_C = 50\text{ mA}$	BCW 60B	$h_{FE}$	70	–
	BCW 60C	$h_{FE}$	90	–
	BCW 60D	$h_{FE}$	100	–
Base-Emitter voltage – Basis-Emitter-Spannung <sup>1)</sup>				
$V_{CE} = 5\text{ V}, I_C = 10\text{ }\mu\text{A}$	$V_{BEon}$	–	520 mV	–
$V_{CE} = 5\text{ V}, I_C = 2\text{ mA}$	$V_{BEon}$	550 mV	650 mV	700 mV
$V_{CE} = 1\text{ V}, I_C = 50\text{ mA}$	$V_{BEon}$	–	780 mV	–
Gain-Bandwidth Product – Transitfrequenz				
$V_{CE} = 5\text{ V}, I_C = 10\text{ mA}, f = 100\text{ MHz}$	$f_T$	100 MHz	250 MHz	–
Collector-Base Capacitance – Kollektor-Basis-Kapazität				
$V_{CB} = 10\text{ V}, I_E = i_c = 0, f = 1\text{ MHz}$	$C_{CB0}$	–	1.7 pF	–
Emitter-Base Capacitance – Emitter-Basis-Kapazität				
$V_{EB} = 0.5\text{ V}, I_C = i_c = 0, f = 1\text{ MHz}$	$C_{EB0}$	–	11 pF	–
Noise figure – Rauschzahl				
$V_{CE} = 5\text{ V}, I_C = 200\text{ }\mu\text{A}, R_G = 2\text{ k}\Omega,$ $f = 1\text{ kHz}, \Delta f = 200\text{ Hz}$	F	–	2 dB	6 dB
Thermal resistance junction to ambient air Wärmewiderstand Sperrschicht – umgebende Luft		$R_{thA}$	420 K/W <sup>2)</sup>	
Recommended complementary PNP transistors Empfohlene komplementäre PNP-Transistoren		BCW 61 series		
Marking – Stempelung	BCW 60B = AB	BCW 60C = AC	BCW 60D = AD	

<sup>1)</sup> Tested with pulses  $t_p = 300\text{ }\mu\text{s}$ , duty cycle  $\leq 2\%$  – Gemessen mit Impulsen  $t_p = 300\text{ }\mu\text{s}$ , Schaltverhältnis  $\leq 2\%$

<sup>2)</sup> Mounted on P.C. board with  $3\text{ mm}^2$  copper pad at each terminal  
Montage auf Leiterplatte mit  $3\text{ mm}^2$  Kupferbelag (Lötpad) an jedem Anschluß